

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

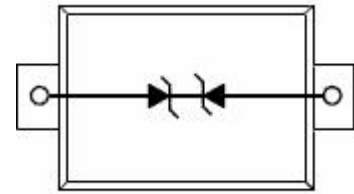


PLED

Product data sheet

Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies



SOD- 523

Features

- Small Body Outline Dimensions
- Low Body Height
- Peak Power up to 200 Watts @ 8 x 20 μ s Pulse
- Low Leakage current
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000-4-4 Level 4 EFT Protection

ORDERING INFORMATION

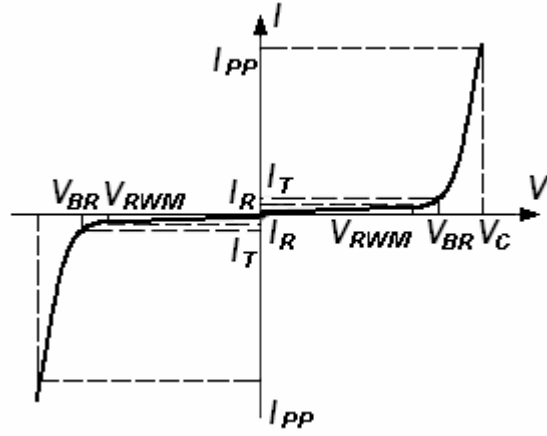
Device	Package	Shipping
MSESD5D3V3C	SOD-523	3000/Tape & Reel

Absolute Ratings (T_{amb}=25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20 μ s)	200	W
T _L	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +155	°C
T _{op}	Operating Temperature Range	-40 to +125	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)	air discharge ± 15 contact discharge ± 8	KV
	IEC61000-4-4 (EFT)	40	A
	ESD Voltage	Per Human Body Model	16 KV

Electrical Parameter

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T



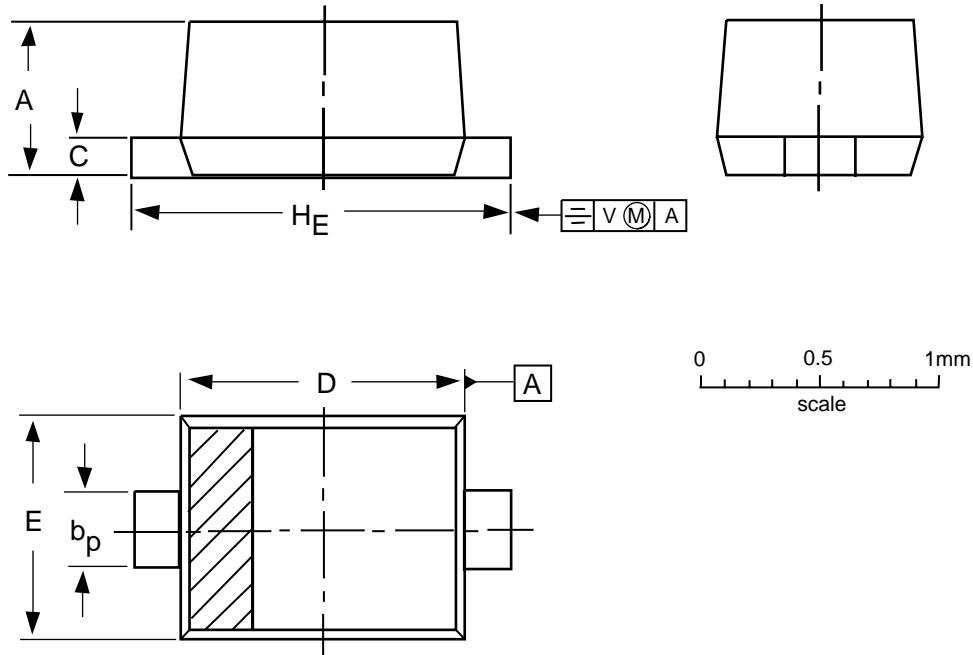
Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified. VF = 0.9V at IF = 10mA

Device	V_{RWM} (V)	I_R (uA) @ V_{RWM}	V_{BR} (V) @ I_T (Note 1)	I_T	V_C (V) @ $I_{PP}=5 A^*$	V_C (V) @ Max I_{PP}^*	I_{PP} (A)*	P_{PK} (W)*	C (pF)
	Max	Max	Min	mA	Typ	Max	Max	Max	Typ
MSESD5D3V3C	3.3	1	5.0	1.0	11.6	18.6	9.4	174	25

*Surge current waveform per Figure 1.

- V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C.

SOD-523



DIMENSIONS (mm are the original dimensions)

UNIT	A	b _p	c	D	E	H _E	V
mm	0.7	0.35	0.2	1.3	0.9	1.7	0.15
	0.5	0.25	0.1	1.1	0.7	1.5	

Note

1. The marking bar indicates the cathode.

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